

MacDermid Alpha Releases HELIOFAB AG 7921 High-Brightness Silver for Leadframe Based LED Packages

(Waterbury, CT USA) – November 26th, 2020 – MacDermid Alpha Electronics Solutions, a global leader in specialty materials for electronics, announces the release of HELIOFAB AG 7921, a high brightness silver electroplating process for leadframe based LED packages.

Reflectivity of the leadframe surface is a key factor in LED packaging design. Leadframe based LED package manufacturers require a high brightness silver spot plating process that ensures a proper surface for die attach and wire bonding during assembly. The silver finish must also provide lasting reflectivity during end use performance.

MacDermid Enthone's HELIOFAB AG 7921 spot silver electroplating process consistently deposits highly reflective silver with measured GAM values around 2.0 over a wide current density window of 10 to 70 ASD. The bath produces a stable deposit over the standard 100 AH/L industry bath life metric. The deposit passes all standard testing for LED performance such as 1000-hour luminous decay as well as assembly functional testing for gold wire bond pull and die attach shear strength. The process is currently in high volume production and is specified for OEM use in leadframe LED manufacturing.

For more information on HELIOFAB AG 7921, please visit [MacDermidAlpha.com](https://www.MacDermidAlpha.com)

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